Polymers in Electronics
New International Conference

Organised by

Smithers Rapra Ltd

Munich, Germany
30-31 January 2007
SESSION 1. TRENDS AND GROWTH

Paper 1  Plastics in Electronics - the CEE market
Kalman Wappel, Eastern and Central European Business Development Ltd., Hungary

SESSION 2. CONDUCTIVE POLYMERS

Paper 2  Electrically conductive polymer blends filled with low melting metal alloys
Prof. Dr.-Ing. Dr.-Ing. E.h. Walter Michaeli & Dipl.-Ing. Tobias Pfefferkorn, Institute of Plastics Processing at RWTH Aachen University (IKV), Germany

Paper 3  Development and applications of nano- and microscale layers of conductive polymers applied onto various surfaces
Dr. Jamshid Avloni & Ryan Lau, Eeonyx Corporation & Dr. Arthur Henn, Marktek Inc., USA

Paper 4  Conducting polymer nanocomposites in EMI shielding/radar absorption applications
Matt Aldissi, Fractal Systems Inc., USA

Paper 5  Inherently conductive polyaniline for electronics applications
Jukka Perento, Panipol, Finland

SESSION 3. NEW DEVELOPMENTS IN FLAME RETARDED POLYMERS FOR ELECTRONICS

Paper 6  Sustainable flame retardants – beyond fire safety, RoHS, and WEEE compliance
Troy DeSoto & Veronique Steukers, Albemarle Corporation, Belgium & Kumar Kumar, Albemarle Corporation, USA

Paper 7  Phosphinates, the flame retardants for polymers in electronics
Dr. Sebastian Hörold, Imar Schmitt, Mathias Dietz, Jerome De Boysere, Clariant Produkte GmbH, Germany

Paper 8  Fire retardancy of polymers in electronics, a scientific approach
SESSION 4. POLYMERS IN SUBSTRATES, ASSEMBLY AND RELIABILITY

Paper 9 An overview of polymers as key enablers in electronics assembly
Prof. Martin Goosey, IeMRC, UK

Paper 10 New epoxy resins for printed wiring board application
Dr. Bernd Hoevel, Dr. Ludovic Valette & Dr. Joseph Gan, Dow Deutschland Anlagengesellschaft mbH, Germany

Paper 11 Printed circuit boards for lead free soldering, materials and failure mechanisms
Per Johander, Per-Erik Tegehall, Abelrahim Ahmed Osman, Göran Wetter & Dag Andersson, IVF Industrial Research & Development Corporation, Sweden

Paper 12 Selection and qualification of polymers for rigid and flexible interconnect applications
Florian Schuessler, Prof. Dr.-Ing. Klaus Feldmann & Thomas Bigl, Institute for Manufacturing Automation and Production Systems (FAPS), Germany

Paper 13 Macromelt molding - low pressure adhesive injection molding
Olaf Muendelein, Henkel GmbH, Germany

Paper 14 Conformal coating resistance to organic and inorganic contaminants
Dr. Christopher Hunt, National Physical Laboratory, UK

SESSION 5. POLYMER FORMULATION AND RECYCLING FOR ELECTRONICS APPLICATIONS

Paper 15 Additives: the way to tailor-made plastics for E&E applications
Dr. Markus C. Grob, Eelco Dekker & Dr. Wolfgang Diegritz, Ciba Specialty Chemicals Inc., Switzerland

Paper 16 Polymer recycling from WEEE - rapid assessment of electronic product enclosure plastics for improved resource management
Prof. Gary Stevens et al, Gnosys/Surrey University, UK

Paper 17 Polymers in WEEE – A ‘sustainable’ raw material resource
Keith Freegard, Axion Recycling Ltd, UK

SESSION 6. POLYMERS AND PRINTED ELECTRONICS

Paper 18 Printed electronics: market opportunities and technical challenges
Mark Hutton & Nick Pearne, BPA Consulting, UK

Paper 19 Inkjet printing of electronics
Steve Jones, Printed Electronics Limited, UK

Paper 20 Flexible printing process for bespoke film based FCBs on polymer foil by combining laser technology, printing technology and electroplating "Flextronic"
Frits Feenstra, TNO Science & Industry, The Netherlands & Juergen Hackert, Vipem GmbH, Germany

Paper 21 Printed interconnects and batteries
Darren Southee, Gareth Hay, Peter Evans & David Harrison, Brunel University, UK